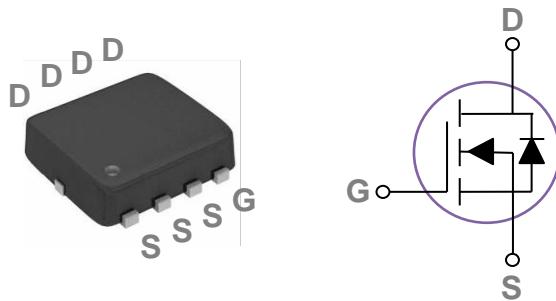


## General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

## PPAK3X3 Pin Configuration



BVDSS	RDS(ON)	ID
65V	17.5mΩ	32A

## Features

- 65V,32A,  $RDS(ON) = 17.5m\Omega$  @ $VGS = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

## Applications

- Motor Drive
- Power Tools
- LED Lighting
- Quick Charger

## Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	65	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	32	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	20.2	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	128	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	45	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	30	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	46	W
	Power Dissipation – Derate above $25^\circ C$	0.37	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

## Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2.7	$^\circ C/W$

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	65	---	---	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=65\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=52\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>3</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=10\text{A}$	---	14.5	17.5	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=5\text{A}$	---	17.5	23	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	1	1.7	2.5	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=3\text{A}$	---	10	---	S

**Dynamic and switching Characteristics**

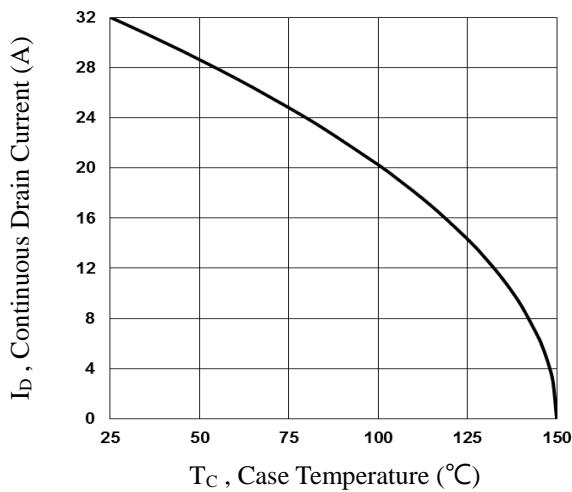
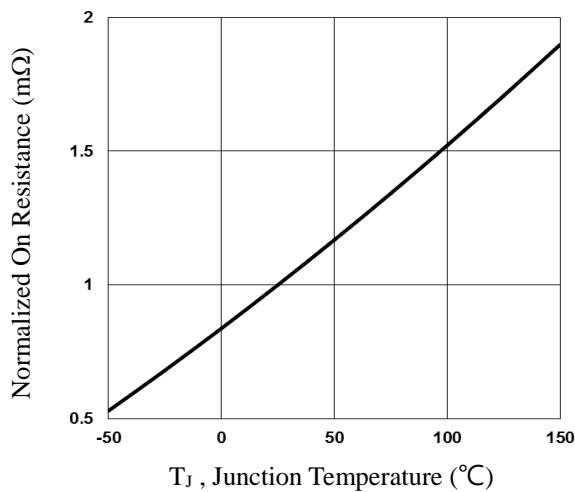
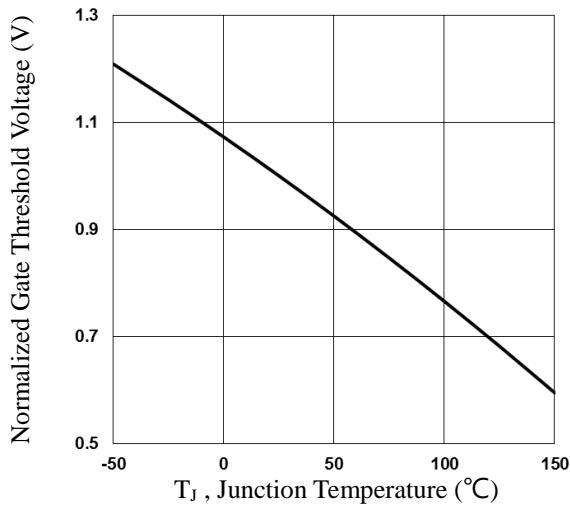
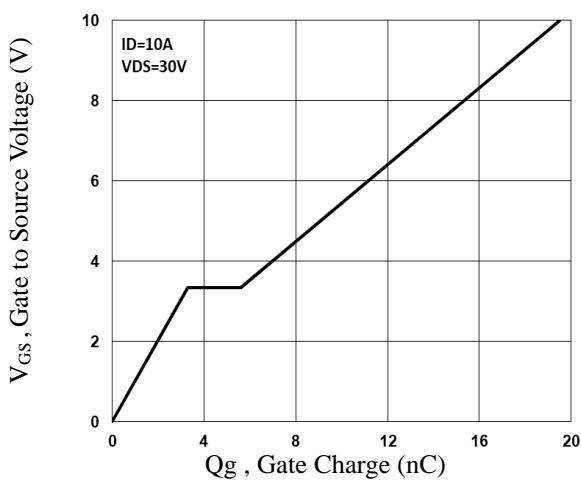
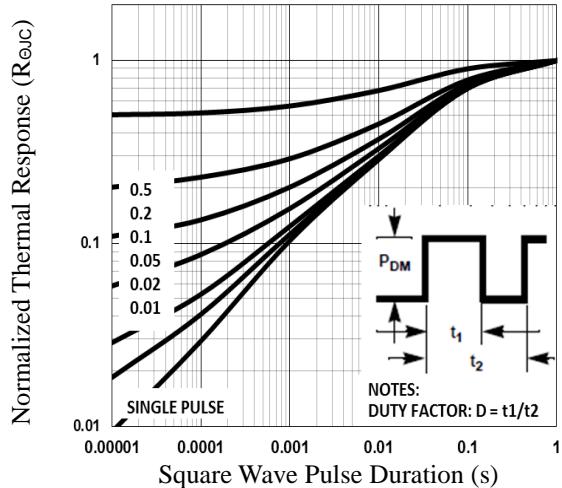
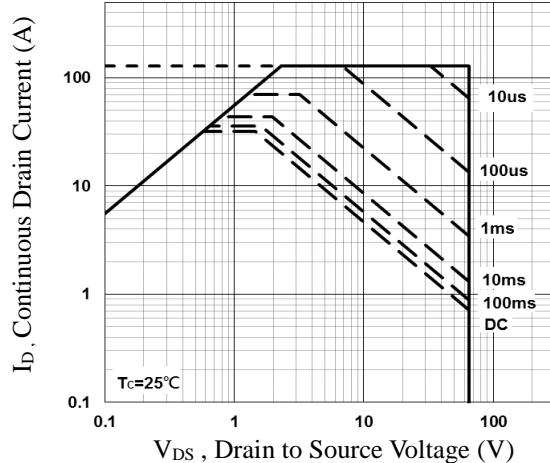
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=10\text{A}$	---	19.5	40	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3, 4</sup>		---	3.3	7	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3, 4</sup>		---	2.3	5	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$ $I_D=1\text{A}$	---	8.6	16	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	24.2	48	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3, 4</sup>		---	32.3	64	
$T_f$	Fall Time <sup>3, 4</sup>		---	7.9	16	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	1310	2600	pF
$C_{\text{oss}}$	Output Capacitance		---	110	220	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	70	140	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	1.9	3.8	$\Omega$

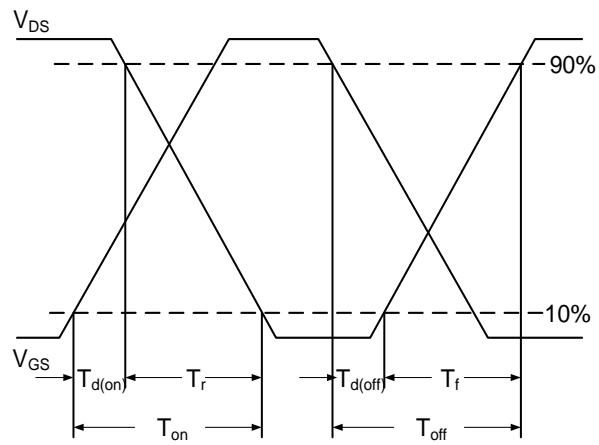
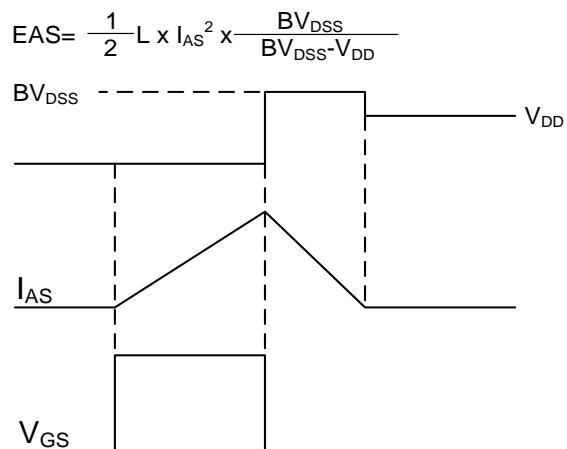
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	32	A
			---	---	64	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>3</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{\text{rr}}$	Reverse Recovery Time	$V_{\text{GS}}=0\text{V}, I_s=1\text{A}$ , $\text{di}/\text{dt}=100\text{A}/\mu\text{s}$ $T_J=25^\circ\text{C}$	---	19	---	ns
			---	5	---	nC

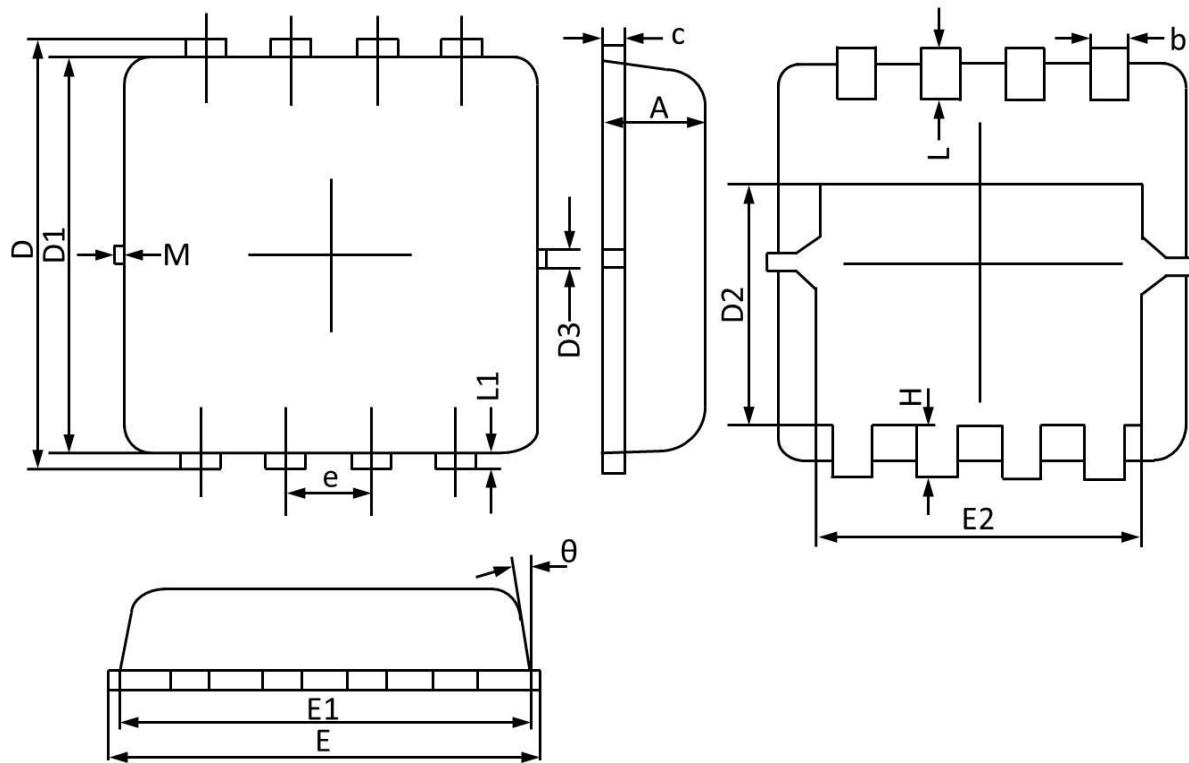
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=30\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. TC**

**Fig.2 Normalized RDSON vs. TJ**

**Fig.3 Normalized Vth vs. TJ**

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Response**

**Fig.6 Maximum Safe Operation Area**


**Fig.7 Switching Time Waveform**

**Fig.8 EAS Waveform**

## PPAK3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.013
c	0.100	0.250	0.004	0.009
D	3.250	3.450	0.128	0.135
D1	3.000	3.200	0.119	0.125
D2	1.780	1.980	0.070	0.077
D3	0.130 REF		0.005 REF	
E	3.200	3.400	0.126	0.133
E1	3.000	3.200	0.119	0.125
E2	2.390	2.590	0.094	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.011	0.019
L	0.300	0.500	0.011	0.019
L1	0.130 REF		0.005 REF	
θ	0°	12°	0°	12°
M	0.150 REF		0.006 REF	